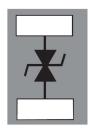


40 V single line ESD protection with ultra-low capacitance



0201 package



Product status link

ESDU401-1BF4

Features

- Ultra Low capacitance : 1 pF
- · Bidirectional device
- High working voltage : 40 V
- Low leakage current: 50 nA max.
- 0201 package size compatible
- Ultra small PCB area: 0.18 mm²
- Low clamping voltage: 105 V at 16 A Ipp TLP
- · Halogen free and RoHS compliant component
- Exceeds IEC 61000-4-2 level 4 standard:
 - ±16 kV (air discharge)
 - ±9.5 kV (contact discharge)

Application

Where transient over voltage protection in ESD sensitive equipment is required, such as:

- Smartphones, mobile phones and accessories
- · Tablets and notebooks
- · Portable multimedia devices and accessories
- · Wearable, home automation, healthcare
- Highly integrated systems

Description

The ESDU401-1BF4 is high voltage, ultra low capacitance bidirectional single line TVS diode designed to protect the data line or other I/O ports against ESD transients.

The device is ideal for all applications where both reduced line capacitance and board space saving are required.



1 Characteristics

Table 1. Absolute maximum ratings (T_{amb} = 25 °C)

Symbol		Value	Unit		
V	Dook pulso voltago	IEC 61000-4-2 contact discharge	±9.5	kV	
V _{pp}	Peak pulse voltage	IEC 61000-4-2 air discharge	±16	KV	
P _{pp}	Peak pulse power (8/20 µ	40	W		
I _{pp}	Peak pulse current (8/20	0.7	Α		
Tj	Operating junction tempe	-55 to +150			
T _{stg}	Storage junction tempera	-65 to +150	°C		
TL	Maximum lead temperatu	260			

Figure 1. Electrical characteristics (definitions)

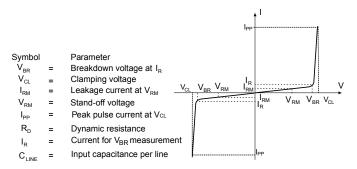


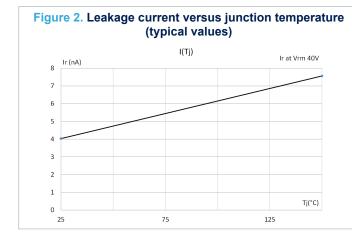
Table 2. Electrical characteristics (values) (T_{amb} = 25° C)

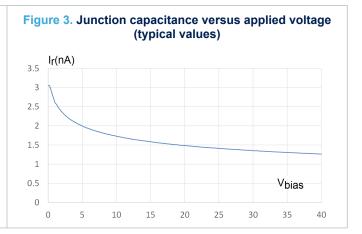
Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
V _{BR}	I _R = 1 mA		41	44	46	V
I _{RM}	Leakage current	V _{RM} = 40 V			50	nA
V _{CL}	Clamping voltage	IEC 61000-4-2, 8 kV contact discharge measured after 30 ns		105		V
V _{CL}	Clamping voltage	8/20 μs waveform, I _{PP} = 0.7 A		50		V
R _D	Dynamic resistance	Pulse duration 100 ns		3.5		Ω
C _{LINE}	Line capacitance	V _{LINE} = 40 V, F = 1 MHz, V _{OSC} = 30 mV		1.1	1.3	pF

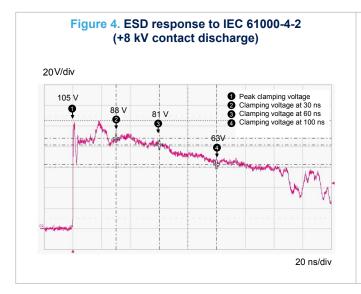
DS13060 - Rev 1 page 2/10



1.1 Characteristics (curves)







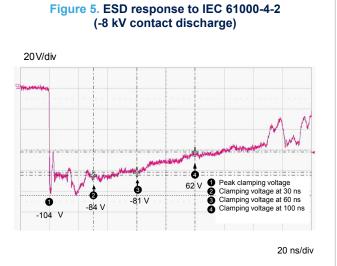
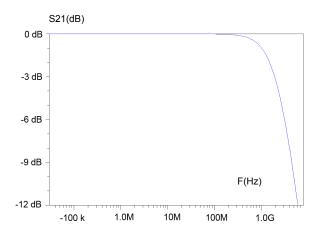


Figure 6. S21 attenuation measurement result



DS13060 - Rev 1 page 3/10



Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 ST0201 package information

Figure 7. ST0201 package outline

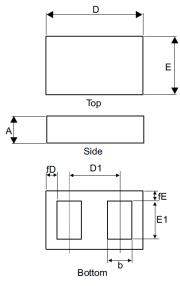


Table 3. ST0201 package mechanical data

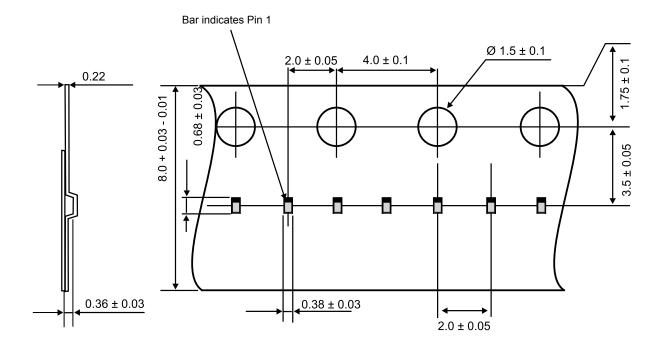
		Dimensions					
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	0.280	0.300	0.320	0.0110	0.0118	0.0126	
b	0.125	0.140	0.155	0.0049	0.0055	0.0061	
D	0.570	0.600	0.630	0.0224	0.0236	0.0248	
D1		0.350			0.0138		
Е	0.270	0.300	0.330	0.0106	0.0118	0.0130	
E1	0.175	0.190	0.205	0.0069	0.0075	0.0081	
fD	0.040	0.055	0.070	0.0015	0.0021	0.0028	
fE	0.040	0.055	0.070	0.0115	0.0021	0.0028	

Note: Marking can be rotated by 90° or 180° to differentiate assembly location.

DS13060 - Rev 1 page 4/10



Figure 8. Tape and reel specification



DS13060 - Rev 1 page 5/10

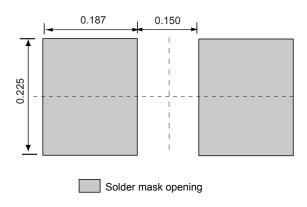


3 Recommendation on PCB assembly

3.1 Footprint

- 1. Footprint in mm
 - a. SMD footprint design is recommended.

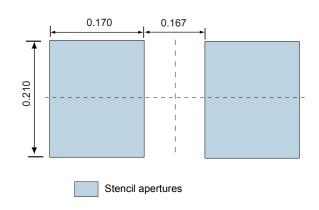
Figure 9. Footprint in mm



3.2 Stencil opening design

- 1. Reference design
 - a. Stencil opening thickness: 75 µm / 3 mils

Figure 10. Recommended stencil window position in mm



DS13060 - Rev 1 page 6/10



3.3 Solder paste

- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed.
- 4. Use solder paste with fine particles: powder particle size 20-38 μm.

3.4 Placement

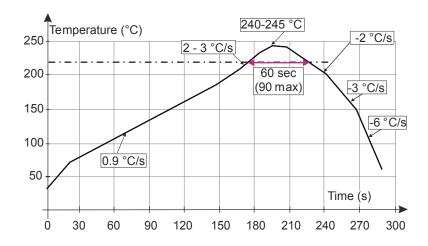
- 1. Manual positioning is not recommended.
- 2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
- 3. Standard tolerance of ±0.05 mm is recommended.
- 4. 1.0 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
- 5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
- 6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.5 PCB design preference

- 1. To control the solder paste amount, the closed via is recommended instead of open vias.
- 2. The position of tracks and open vias in the solder area should be well balanced. A symmetrical layout is recommended, to avoid any tilt phenomena caused by asymmetrical solder paste due to solder flow away.

3.6 Reflow profile

Figure 11. ST ECOPACK recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

DS13060 - Rev 1 page 7/10



4 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
ESDU401-1BF4	9(1)	ST0201	0.116 mg	15000	Tape and reel

^{1.} The marking can be rotated by multiples of 90° to differentiate assembly location

DS13060 - Rev 1 page 8/10



Revision history

Table 5. Document revision history

Date	Revision	Changes
30-Sep-2019	1	First issue.

DS13060 - Rev 1 page 9/10



IMPORTANT NOTICE - PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2019 STMicroelectronics - All rights reserved

DS13060 - Rev 1 page 10/10

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for ESD Suppressors / TVS Diodes category:

Click to view products by STMicroelectronics manufacturer:

Other Similar products are found below:

60KS200C D12V0H1U2WS-7 D18V0L1B2LP-7B 82356050220 D5V0M5U6V-7 NTE4902 P4KE27CA P6KE11CA P6KE39CA-TP
P6KE8.2A SA110CA SA60CA SA64CA SMBJ12CATR SMBJ8.0A SMLJ30CA-TP ESD101-B1-02ELS E6327 ESD112-B1-02EL E6327
ESD119B1W01005E6327XTSA1 ESD5V0J4-TP ESD5V0L1B02VH6327XTSA1 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF
3.0SMCJ33CA-F 3.0SMCJ36A-F HSPC16701B02TP D3V3Q1B2DLP3-7 D55V0M1B2WS-7 DESD5V0U1BL-7B DRTR5V0U4SL-7
SCM1293A-04SO ESD200-B1-CSP0201 E6327 ESD203-B1-02EL E6327 SM12-7 SMF8.0A-TP SMLJ45CA-TP CEN955 W/DATA
82350120560 82356240030 VESD12A1A-HD1-GS08 CPDUR5V0R-HF CPDUR24V-HF CPDQC5V0U-HF CPDQC5V0USP-HF
CPDQC5V0-HF D1213A-01LP4-7B D1213A-02WL-7 ESDLIN1524BJ-HQ 5KP100A